

## NPN 1 GHz wideband transistor

T-3H17

 BFW92

PHILIPS INTERNATIONAL

56E D ■ 7110826 0046029 981 ■ PHIN

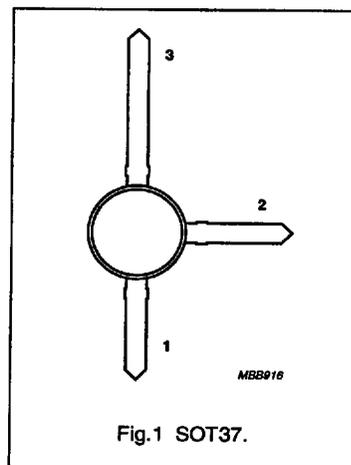
## DESCRIPTION

NPN transistor in a plastic SOT37 envelope.

It has a low noise over a wide current range, a very high power gain and good intermodulation properties. It is primarily intended for wideband aerial amplifiers (40 to 860 MHz), channel and band aerial amplifiers for band I, II, III and IV/V (40 to 860 MHz), television distribution amplifiers and low noise wideband vertical amplifiers in high speed oscilloscopes.

## PINNING

PIN	DESCRIPTION
Code: BFW92/02	
1	base
2	emitter
3	collector



## QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	—	25	V
$V_{CEO}$	collector-emitter voltage	open base	—	15	V
$I_{CM}$	peak collector current	$f > 1$ MHz	—	50	mA
$P_{tot}$	total power dissipation	up to $T_s = 155$ °C (note 1)	—	300	mW
$f_T$	transition frequency	$I_C = 25$ mA; $V_{CE} = 5$ V; $f = 500$ MHz; $T_j = 25$ °C	1.6	—	GHz
$C_{re}$	feedback capacitance	$I_C = 2$ mA; $V_{CE} = 5$ V; $f = 1$ MHz; $T_{amb} = 25$ °C	0.6	—	pF
F	noise figure	$I_C = 2$ mA; $V_{CE} = 5$ V; $R_s = 50$ Ω; $f = 500$ MHz; $T_{amb} = 25$ °C	4	—	dB
$G_p$	power gain	$I_C = 10$ mA; $V_{CE} = 10$ V; $f = 800$ MHz; $T_{amb} = 25$ °C	11	—	dB
$P_O$	output power	$I_C = 10$ mA; $V_{CE} = 10$ V; $f = 800$ MHz; $T_{amb} = 25$ °C; $d_{im} = -30$ dB; VSWR at output < 2	8	—	mW

## Note

- $T_s$  is the temperature at the soldering point of the collector lead.

## NPN 1 GHz wideband transistor

T-31-17

BFW92

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## LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	-	25	V
$V_{CEO}$	collector-emitter voltage	open base	-	15	V
$V_{EBO}$	emitter-base voltage	open collector	-	2.5	V
$I_C$	DC collector current		-	25	mA
$I_{CM}$	peak collector current	$f > 1$ MHz	-	50	mA
$P_{tot}$	total power dissipation	up to $T_s = 155$ °C (note 1)	-	300	mW
$T_{stg}$	storage temperature		-65	150	°C
$T_j$	junction temperature		-	175	°C

## THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
$R_{th(j-s)}$	thermal resistance from junction to soldering point	up to $T_s = 155$ °C (note 1)	65 K/W

## Note

- $T_s$  is the temperature at the soldering point of the collector lead.

## CHARACTERISTICS

 $T_j = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$I_E = 0$ ; $V_{CB} = 10$ V	-	-	50	nA
$h_{FE}$	DC current gain	$I_C = 2$ mA; $V_{CE} = 1$ V	25	90	-	
		$I_C = 25$ mA; $V_{CE} = 1$ V	25	90	-	
$f_T$	transition frequency	$I_C = 2$ mA; $V_{CE} = 5$ V; $f = 500$ MHz	-	1	-	GHz
		$I_C = 25$ mA; $V_{CE} = 5$ V; $f = 500$ MHz	-	1.6	-	GHz
$C_c$	collector capacitance	$I_E = I_B = 0$ ; $V_{CB} = 10$ V; $f = 1$ MHz	-	0.7	-	pF
$C_e$	emitter capacitance	$I_C = I_B = 0$ ; $V_{EB} = 0.5$ V; $f = 1$ MHz	-	1.5	-	pF
$C_{re}$	feedback capacitance	$I_C = 2$ mA; $V_{CE} = 5$ V; $f = 1$ MHz; $T_{amb} = 25$ °C	-	0.6	-	pF
F	noise figure	$I_C = 2$ mA; $V_{CE} = 5$ V; $R_s = 50$ Ω; $f = 500$ MHz; $T_{amb} = 25$ °C	-	4	-	dB
$G_p$	power gain	$I_C = 10$ mA; $V_{CE} = 10$ V; $f = 800$ MHz; $T_{amb} = 25$ °C	-	11	-	dB
$P_o$	output power	note 1	-	8	-	mW

## Note

- $I_C = 10$  mA;  $V_{CE} = 10$  V;  $f = 800$  MHz;  $T_{amb} = 25$  °C;  $d_{im} = -30$  dB; VSWR at output  $< 2$   
 $f_p = 798$  MHz;  $f_q = 802$  MHz;  
measured at  $f_{(p-q)} = 806$  MHz.

